



Product Change Notification / LIAL-02EMAI368

Date:

16-Nov-2020

Product Category:

Access Networks, Broadband Gateway, Line Drivers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3886.005, and 3886.006 Final Notice: Qualification of MMT as an additional assembly site for selected Microsemi products available in 28L VQFN (4x5x1mm) and 16L VQFN (4x4x1mm) packages

Affected CPNs:

[LIAL-02EMAI368_Affected_CPN_11162020.pdf](#)
[LIAL-02EMAI368_Affected_CPN_11162020.csv](#)

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MMT as an additional assembly site for selected Microsemi products available in 28L VQFN (4x5x1mm) and 16L VQFN (4x4x1mm) packages.

Pre Change:

Assembled at ASEM using palladium coated copper wire (PdCu) bond wire or palladium coated copper wire with gold flash (CuPdAu) bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material or assembled at UNIC using palladium coated copper wire (PdCu) bond wire, 8290 die attach, and G770HP mold compound material.

Post Change:

Assembled at ASEM using palladium coated copper wire (PdCu) bond wire or palladium coated copper wire with gold flash

(CuPdAu) bond wire, CRM1076DS die attach, and CEL-9240HF10AK-G1 mold compound material or assembled at UNIC using palladium coated copper wire (PdCu) bond wire, 8290 die attach, and G770HP mold compound material or assembled at MMT using or palladium coated copper wire with gold flash (CuPdAu) bond wire wire material, 3280 die attach, and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change			Post Change			
Assembly Site	ASE Group -Malaysia (ASEM)		Unisem Chengdu Co.,Ltd. (UNIC)	ASE Group -Malaysia (ASEM)		Unisem Chengdu Co.,Ltd. (UNIC)	Microchip Technology Thailand (Branch) (MMT)
Wire material	PdCu	CuPdAu	PdCu	PdCu	CuPdAu	PdCu	CuPdAu
Die attach material	CRM1076DS		8290	CRM1076DS		8290	3280
Molding compound material	CEL-9240HF10AK-G1		G770HP	CEL-9240HF10AK-G1		G770HP	G700LTD
Lead frame material	A194		A194	A194		A194	A194
LF drawing comparison	See Pre and Post Change attachment.						

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity and on-time delivery by qualifying MMT as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date)December 7, 2020 (date code: 2050)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2020				December 2020				
Workweek	45	46	47	48	49	50	51	52	53
Final PCN Issue Date			X						
Qual Report Availability			X						
Estimated						X			

Implementation Date									
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Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:**November 16, 2020:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on December 7, 2020.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-02EMAI368 Qual Report.pdf](#)
[PCN_LIAL-02EMAI368 _Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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